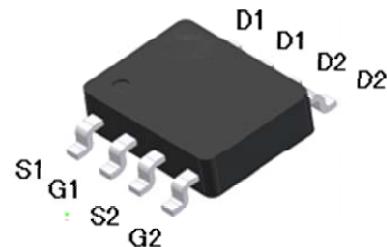
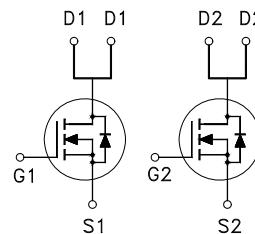


Dual N-Channel Logic Level Enhancement Mode Field Effect Transistor
Product Summary:

BV_{DSS}	30V
$R_{DS(on)}$ (MAX.)	32mΩ
I_D	6.5A


Pb-Free Lead Plating & Halogen Free

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNIT
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	6.5	A
		5.5	
Pulsed Drain Current ¹	I_{DM}	26	
Power Dissipation	P_D	2	W
		0.8	
Operating Junction & Storage Temperature Range	T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		25	°C / W
Junction-to-Ambient ³	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

³62.5°C / W when mounted on a 1 in² pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0	1.5	3.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, T_j = 125^\circ\text{C}$			25	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 5\text{V}, V_{\text{GS}} = 10\text{V}$	6.5			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 6.5\text{A}$		28	32	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 5.5\text{A}$		50	60	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 6.5\text{A}$		14		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1\text{MHz}$		323		pF
Output Capacitance	C_{oss}			75		
Reverse Transfer Capacitance	C_{rss}			53		
Total Gate Charge ^{1,2}	Q_g	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 6.5\text{A}$		7.1		nC
Gate-Source Charge ^{1,2}	Q_{gs}			1.1		
Gate-Drain Charge ^{1,2}	Q_{gd}			2.1		
Turn-On Delay Time ^{1,2}	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 10\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GS}} = 6\Omega$		8		nS
Rise Time ^{1,2}	t_r			12		
Turn-Off Delay Time ^{1,2}	$t_{\text{d}(\text{off})}$			28		
Fall Time ^{1,2}	t_f			15		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_S				2.3	A
Pulsed Current ³	I_{SM}				9.2	
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{\text{GS}} = 0\text{V}$			1.3	V

¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

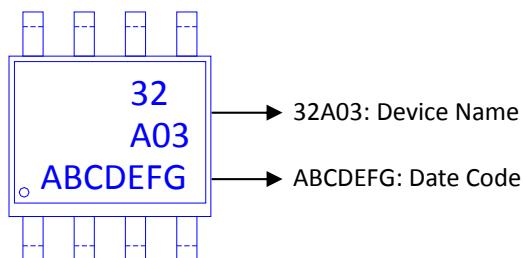
²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

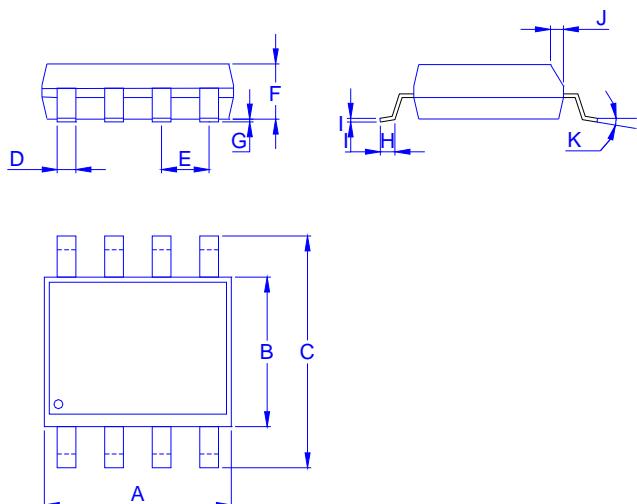
Ordering & Marking

Information:

Device Name: LB32N03HD for SOP-8



Outline Drawing



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K
Min.	4.70	3.70	5.80	0.33		1.20	0.08	0.40	0.19	0.25	0°
Typ.					1.27						
Max.	5.10	4.10	6.20	0.51		1.62	0.28	0.83	0.26	0.50	8°

TYPICAL CHARACTERISTICS

